	Hits	Search Text	DBs
1	35	polyimide) same (etch\$4 or RIE)) and ((photoresist or resist or photosensitive) same (pattern or mask) same develop\$4 same (expos\$4 or irradiat\$4 or illuminate or	

	Hits	Search Text	DBs
2	36	((photoresist or resist or photosensitive) same (pattern or mask) same develop\$4 same (expos\$4 or irradiat\$4 or illuminate or	US-PGPUB; USPAT; FPRS; EPO;

	Hits	Search Text	DBs
3	263	polyimide or (Silicon near6 nitride) or (hard near9 mask)) same (etch\$4 or RIE)) and ((fill\$4 or deposit\$4 or coat\$4) same (window or opening or (bit\$3]ine	
4	19	hole or window) near16 (dielectric or BPSG)) same ((conductive or	USPAT; FPRS; EPO; JPO; DERWENT;

	Hits	Search Text	DBs
5	23	same (etch\$4 or RIE)) and ((fill\$4 or deposit\$4 or coat\$4) same (window or opening or (bit\$3line near6 contact near4 window) or (aspect near6 ratio) or (contact near9 hole)) same (conductive or metal\$4 or polysilicon or poly\$i or tungsten or ("W" near3 plug))) and ((isolation or TEOS) same (layer or deposit\$4 or coat\$4 or film or form\$3) same ((open\$4 or hole or window) near16 (dielectric or BPSG))) and (planariz\$6 or CMP or (chemical near6 mechanical near6 polish\$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
6	3	(("20050026409") or ("6696355") or ("5795823")).PN.	US-PGPUB; USPAT

	Hits	Search Text	DBs
7	36	and ((photoresist or resist or photosensitive) same (pattern or mask) same develop\$4 same (expos\$4 or irradiat\$4 or illuminate or photolithograph\$4)) and ((fill\$4	